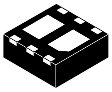
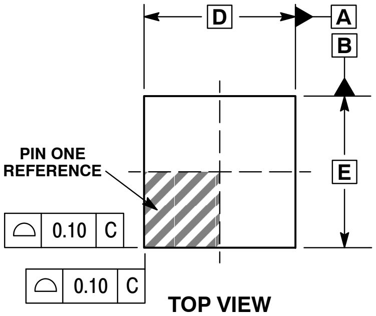
WDFN6 2x2, 0.65P
CASE 506AN
ISSUE G

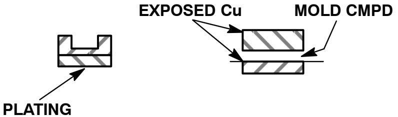


SCALE 4:1

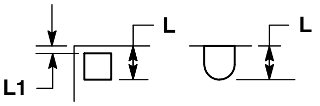
DATE 22 AUG 2013



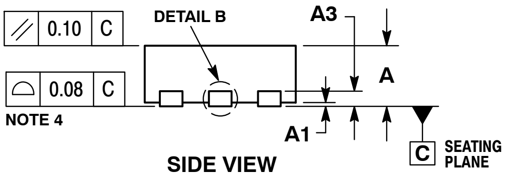
TOP VIEW



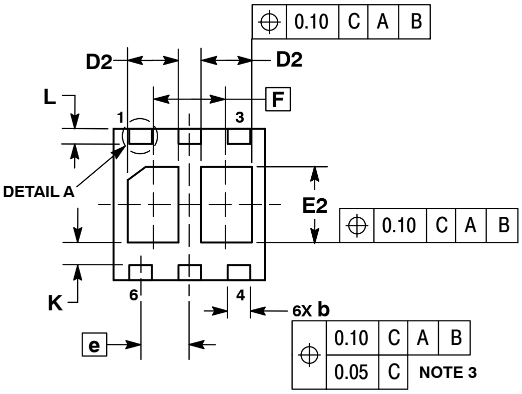
DETAIL B
OPTIONAL CONSTRUCTIONS



DETAIL A
OPTIONAL CONSTRUCTIONS



SIDE VIEW



BOTTOM VIEW

STYLE 1:
PIN 1. SOURCE 1
2. GATE 1
3. DRAIN 2
4. SOURCE 2
5. GATE 2
6. DRAIN 1

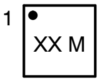
STYLE 2:
PIN 1. ANODE
2. N/C
3. DRAIN
4. SOURCE
5. GATE
6. CATHODE

STYLE 3:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. DRAIN 2
5. GATE 2
6. DRAIN 1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	2.00 BSC	
D2	0.57	0.77
E	2.00 BSC	
E2	0.90	1.10
e	0.65 BSC	
F	0.95 BSC	
K	0.25 REF	
L	0.20	0.30
L1	---	0.10

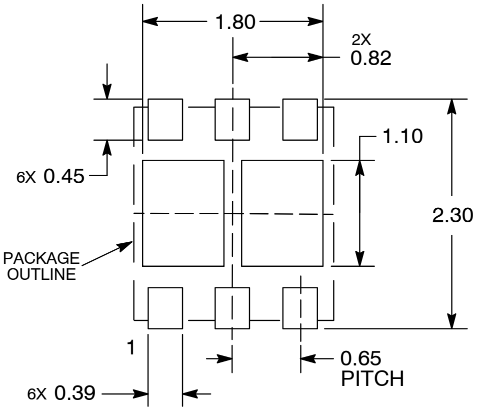
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERMASK DEFINED MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY JAY LIU.	23 JUN 2005
A	DELETED STYLE 1. FIXED DIMENSION K TO 0.25 REF. REQ. BY JAY LIU.	11 OCT 2005
B	CHANGED SOLDERING FOOTPRINT. CHANGED DESCRIPTION TO WDFN6. REQ. BY JAY LIU.	19 JAN 2006
C	ADDED STYLES 1 AND 2. REQ. BY K. JAMES.	25 APR 2006
D	ADDED DIMENSION F, ADDED DETAILS A AND B. CHANGED SOLDERING FOOTPRINT. REQ. BY A. TAM.	24 NOV 2008
E	CORRECTED DIMENSION D2 MAX FROM 0.67 TO 0.77. REQ. BY SW WANG.	20 AUG 2010
F	ADDED STYLE 3. REQ. BY I. CAMBALIZA.	11 SEP 2012
G	MODIFIED DIMENSION F TO BE DISTANCE FROM CENTERS OF EXPOSED PADS. MODIFIED SOLDER FOOTPRINT DIMENSIONS. REQ. BY D. KNUDSEN.	22 AUG 2013

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